<u>S/N 10/808,192</u> <u>PATENT</u>

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Daewoong Suh Examiner: John B. Vigushin

Serial No.: 10/808,192 Group Art Unit: 2841

Filed: March 24, 2004 Docket: 884.C25US1

Title: SOLDERING AN ELECTRONICS PACKAGE TO A MOTHERBOARD

Customer Number: 21186

INFORMATION DISCLOSURE STATEMENT

MS Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 et. seq., the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicant respectfully requests that this Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicant requests that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicant with the next official communication.

Pursuant to 37 C.F.R. §1.97(b), it is believed that no fee or statement is required with the Information Disclosure Statement. However, if an Office Action on the merits has been mailed, the Commissioner is hereby authorized to charge the required fees to Deposit Account No. 19-0743 in order to have this Information Disclosure Statement considered.

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The Examiner is invited to contact the Applicant's Representative at the below-listed telephone number if there are any questions regarding this communication.

Pursuant to 37 C.F.R. 1.98(a)(2), Applicant believes that copies of cited U.S. Patents and Published Applications are no longer required to be provided to the Office. Notification of this change was provided in the United States Patent and Trademark Office OG Notices dated October 12, 2004. Thus, Applicant has not included copies of any US Patents or Published Applications cited with this submission. Should the Office require copies to be provided, Applicant respectfully requests that notice of such requirement be directed to Applicant's belowsigned representative. Applicant acknowledges the requirement to submit copies of foreign patent documents and non-patent literature in accordance with 37 C.F.R. 1.98(a)(2).

Respectfully submitted,

DAEWOONG SUH

By his Representatives,

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By / Andrew Peret

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Substitute for form 1448APTO INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use as many sheets as necessary)	Complete if Known		
	Application Number	10/808,192	
	Filing Date	March 24, 2004	
	First Named Inventor	Suh, Daewoong	
	Group Art Unit	2841	
	Examiner Name	Vigushin, John	
Sheet 1 of 1	Attorney Docket No: 8	384.C25US1	

US PATENT DOCUMENTS				
Examiner Initial *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Filing Date If Appropriate

FOREIGN PATENT DOCUMENTS				
Examiner Initials*	Foreign Document No	Publication Date	Name of Patentee or Applicant of cited Document	T²

	OTHE	R DOCUMENTS - NON PATENT LITERATURE DOCUMENTS	
Examiner Initials*	Cite No 1	include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ^z
		ROMAN, JOHN W., et al., "Low Stress Die Attach by Low Temperature Transient Liquid Phase Bonding", <u>The International Societ for Hybrid Microelectronics (ISHM) Symposium Proceedings, October 1992,</u> (October 1992),1-6	